TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π -MOSV)

TPC8012-H

Switching Regulator Application DC-DC Converters

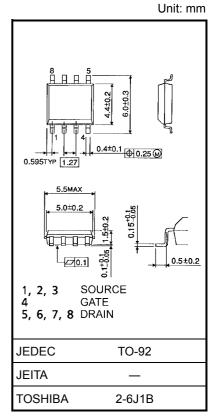
- Low drain-source ON resistance: RDS (ON) = 0.28Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 1.35 \text{ S (typ.)}$
- Low leakage current: $I_{DSS} = 100 \mu A \text{ (max) (V}_{DS} = 200 \text{ V)}$
- Enhancement mode: $V_{th} = 3.0 \text{ to } 5.0 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

Maximum Ratings (Ta = 25°C)

Characte	ristics	Symbol	Rating	Unit	
Drain-source voltage		V_{DSS}	200	V	
Drain-gate voltage (R	$R_{GS} = 20 \text{ k}\Omega$	V_{DGR}	200	V	
Gate-source voltage		V_{GSS}	±30	V	
Drain current	DC (Note 1)	I _D	1.8	Α	
Diam current	Pulse (Note 1)	I_{DP}	7.2	^	
Drain power dissipati	on $(t = 10 s)$ (Note 2a)	P_{D}	1.9	W	
Drain power dissipati	on (t = 10 s) (Note 2b)	P _D	1.0	W	
Single pulse avalanch	ne energy (Note 3)	E _{AS}	2.05	mJ	
Avalanche current		I _{AR}	1.8	Α	
Repetitive avalanche	energy Note 2a) (Note 4)	E _{AR}	0.19	mJ	
Channel temperature	!	T _{ch}	150	°C	
Storage temperature	range	T _{stg}	-55 to 150	°C	

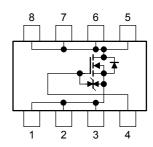
Note: (Note 1), (Note 2), (Note 3), (Note 4) Please see next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.80 g (typ.)

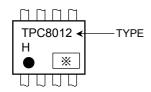
Circuit Configuration



Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R _{th (ch-a)}	65.8	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R _{th (ch-a)}	125	°C/W

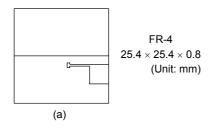
Marking (Note 5)

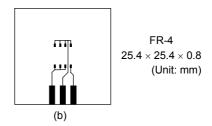


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)





Note 3: V_{DD} = 50 V, T_{ch} = 25°C (initial), L = 1.0 mH, R_G = 25 Ω , I_{AR} = 1.8 A

Note 4: Repetitive rating; pulse width limited by maximum channel temperature

Note 5: • on lower left of the marking indicates Pin 1.

* shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

Electrical Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cur	rent	I _{GSS}	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain cut-OFF cu	rrent	I _{DSS}	V _{DS} = 200 V, V _{GS} = 0 V	_	_	100	μΑ
Drain-source brea	akdown voltage	V _{(BR) DSS}	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	200	_	_	V
Gate threshold vo	oltage	V _{th}	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	3.0	3.0 — 5.0		V
Drain-source ON	resistance	R _{DS} (ON)	V _{GS} = 10 V, I _D = 0.9 A	_	0.28	0.40	Ω
Forward transfer	admittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 0.9 \text{ A}$	0.65	1.35	_	S
Input capacitance		C _{iss}		_	440	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 10 V, V _{GS} = 0 V, f = 1 MHz	_	80	_	
Output capacitance		C _{oss}		_	260	_	
	Rise time	t _r	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	_	23	_	
Conitabilita a tima a	Turn-ON time	t _{on}					
Switching time	Fall time	t _f	Z = 17	_	22		ns
	Turn-OFF time	t _{off}	V _{DD} ≃ 100 V	_	73	_	
Total gate charge (gate-source plus	plus gate-drain)		_				
Gate-source charge 1		Q _{gs1}	I _D = 1.8 A		6		nC
Gate-drain ("mille	r") charge	Q _{gd}		_	5	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Drain reverse current	Pulse	(Note 1)	I _{DRP}	_	_	_	7.2	Α
Forward voltage (diode)			V_{DSF}	$I_{DR} = 1.8 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.5	V

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